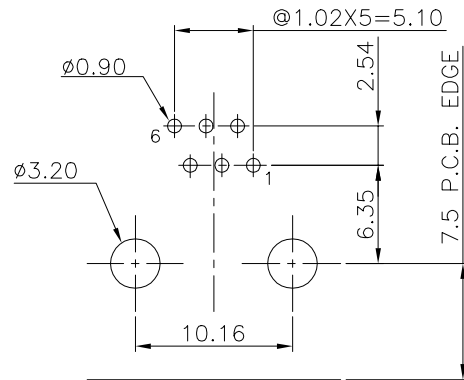
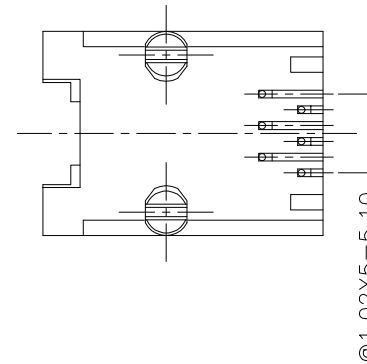
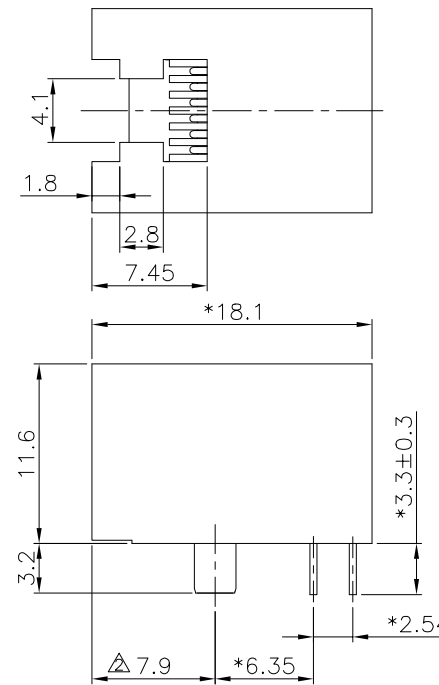
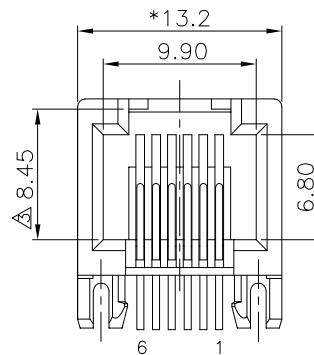
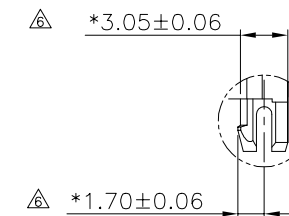
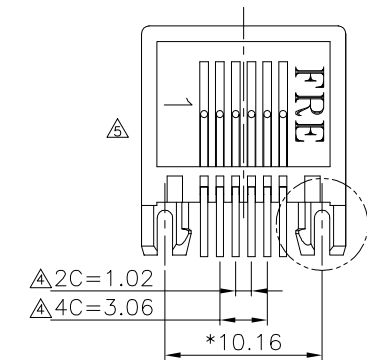




PC Board Layout t=1.60mm
Component Side Shown



REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD
1		DRAWING MODIFY	JACKEY 7/1/99	
2		7.9 was 8.0	JACKEY 7/14/99	
3		Add P/N	LUSHENG 01/16/01	
4		DRAWING MODIFY	CZH 7/15/02	
5		DRAWING MODIFY	CZH 02/08/03	
6		DRAWING MODIFY	SAMMY 02/02/04	
7		Add P/N	Ying 21/05/04	
8		Add P/N	SHE 7/13/04	
9		Add P/N	CXG 5/05/05	



NOTES:

ELECTRICAL:

- VOLTAGE RATING : 150 VAC RMS.
- CURRENT RATING : 1.5 AMP.
- CONTACT RESISTANCE : 20 MILLIOHMS MAX.
- INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
- DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

MECHANICAL:

- HOUSING MATERIAL : GLASS FILLED POLYESTER UL94V-0.
- CONTACT MATERIAL : PHOSPHOR BRONZE $\phi 0.46\text{mm}$.
- PLATING : GOLD PLATING OVER NICKEL.
- OPERATING LIFE : 750 CYCLES MIN.
- PCB RETENTION PRE-SOLDER : 1 LB MIN.
- PCB RETENTION POST-SOLDER: 10 LBS MIN.

ENVIRONMENTAL:

- STORAGE : -40°C TO $+85^{\circ}\text{C}$.
 - OPERATION: -20°C TO 85°C .
- MATES WITH MODULAR PLUG CONFORMING TO
FCC PART 68, SUBPART F.
CUL FILE NO. E163191
PART NUMBER: E536X-300XGX

2- 2C
4- 4C
6- 6C

1- 3u" 2- 6u" 3-15u"
4- 30u" 5-50u" F-Glod flash

MATERIAL OF HS'G :
0- PBT + G.F.BK.
4-FR50 BK
5-FR52 BK

MM (INCH)		DFTO BASS	DATE 8/28/98
TOLERANCES EXCEPT AS NOTED		CHKD	DATE
MM		MFO	DATE
.0 ± 0.2	±	APPVL XLF	DATE 05/05/05
.00 ± 0.15	±	MATERIAL :	
.000 ± 0.075	±	QT'Y :	
ANGLES ± 0.5		FINISH :	
THIRD ANGLE PROJECTION		SCALE : 3 : 1	

FULL RISE ELECTRONIC CO., LTD			
TITLE			
11.5mm SIDE PCB JACK 6P			
DRAWING NO. GE533022		SIZE	REV
/PART NO. SEE NOTE		A3	9
DO NOT SCALE DRAWING		SHEET 1	OF 1